NUP4016

Ultra-Low Capacitance Diode-TVS Array for High Speed Data Line Protection

The NUP4016P5 transient voltage suppressor is designed to protect high speed data lines from ESD. Ultra-low capacitance and high level of ESD protection makes this device well suited for use in USB 2.0 applications.

Features

- Ultra-Low Capacitance (0.5 pF Typical Between I/O Lines and Ground)
- ESD Rating of Class 3B (Exceeding 8 kV) per Human Body model and Class C (Exceeding 400 V) per Machine Model
- Protection for the Following IEC Standards: IEC 61000-4-2 15 kV (contact)
- UL Flammability Rating of 94 V-0
- This is a Pb-Free Device

Typical Applications

- High Speed Communication Line Protection
- USB 2.0 High Speed Data Line and Power Line Protection
- Monitors and Flat Panel Displays
- MP3
- Gigabit Ethernet

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

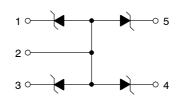
| Rating | Symbol | Value | Unit |
|---|------------------|-----------------------|------|
| Operating Junction Temperature Range | T _J | -40 to +125 | °C |
| Storage Temperature Range | T _{stg} | -55 to +150 | °C |
| Lead Solder Temperature – Maximum (10 Seconds) | T _L | 260 | °C |
| Human Body Model (HBM) Machine Model (MM) IEC 61000-4-2 Contact (ESD) | ESD | 16000 400 15000 | V |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



ON Semiconductor®

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SOT-953 CASE 527AE

MARKING DIAGRAM



4 = Specific Device Code

M = Date Code

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|----------------------|-----------------------|
| NUP4016P5T5G | SOT-953 (Pb-Free) | 4000/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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NUP4016

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-------------------------|----------------|--|-----|-----|-----|------|
| Reverse Working Voltage | V_{RWM} | (Note 1) | | | 5.0 | ٧ |
| Breakdown Voltage | V_{BR} | I _T = 1 mA, (Note 2) | 6.0 | | | V |
| Reverse Leakage Current | I _R | V _{RWM} = 5 V | | | 1.0 | μΑ |
| Junction Capacitance | CJ | V _R = 0 V, f = 1 MHz between I/O Pins and GND | | 0.5 | 0.8 | pF |
| Junction Capacitance | CJ | V _R = 0 V, f = 1 MHz between I/O Pins | | 0.3 | 0.5 | pF |

^{1.} TVS devices are normally selected according to the working peak reverse voltage (V_{RWM}), which should be equal or greater than the DC or continuous peak operating voltage level.

TYPICAL PERFORMANCE CURVES

 $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

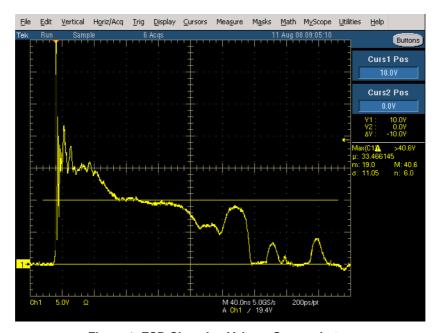


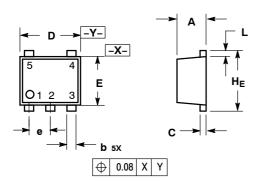
Figure 1. ESD Clamping Voltage Screenshot (8 kV Contact per IEC610000-4-2)

^{2.} V_{BR} is measured at pulse test current I_{T} .

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PACKAGE DIMENSIONS

SOT-953 CASE 527AE-01 ISSUE O

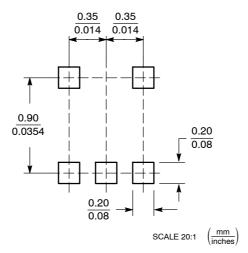


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| | MIL | LIMETE | RS | INCHES | | |
|-----|----------|--------|------|-----------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.34 | 0.37 | 0.40 | | | |
| b | 0.10 | 0.15 | 0.20 | 0.004 | 0.006 | 0.008 |
| С | 0.05 | 0.10 | 0.15 | 0.002 | 0.004 | 0.006 |
| D | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 |
| E | 0.75 | 0.80 | 0.85 | 0.03 | 0.032 | 0.034 |
| е | 0.35 BSC | | | 0.014 BSC | | |
| L | 0.05 | 0.10 | 0.15 | 0.002 | 0.004 | 0.006 |
| HE | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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